

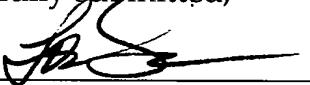
**REMARKS**

This application is a divisional of U.S. patent application 10/188,147, filed July 3, 2002, entitled HIGH ASPECT RATIO CONTACT SURFACES HAVING REDUCED CONTAMINANTS, which is a divisional of U.S. patent application 09/653,561, filed August 31, 2000, entitled METHOD AND MATERIAL FOR REMOVING ETCH RESIDUE FROM HIGH ASPECT RATIO CONTACT SURFACES. The entirety of these parent applications has been incorporated by reference. The specification is amended to change the title and to correct a minor error. Claims 1-44 and 50-53 are cancelled without prejudice to their underlying subject matter since they are the subject of the parent applications.

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to pass this application to issue.

Dated: February 27, 2004

Respectfully submitted,

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